

**Microsemi.**

Power and Microelectronics Group (PMG) – Phoenix Division

Product Change Notification

Date: Friday, November 11, 2011**PCN#:** 140A00202**Subject:** W3H64-XSBX, W3H72-XSBX, W3H72E-XSBXF datasheet changes

Dear Customer,

In an effort to better communicate to you, our user community, we have implemented an e-mail version for our PCN process in addition to our PCN website. While you may receive a notification from us concerning a particular part or part numbers, it is not an indication that you use or have ordered these particular parts, but merely a communication to notify our user community as a whole. Please review your sales orders, POs, records, etc. to determine if this particular PCN impacts your activities or affects your business.

Product Description: DDR2 208 Plastic BGA.

Reason for Change: Specification adjustment based on product performance.

Microsemi Power and Microelectronics Group wishes to inform you of the following products affected:

W3H64M64E-400SBC	W3H64M72E-400SBC	W3H64M72E-400SBCF
W3H64M64E-400SBI	W3H64M72E-400SBI	W3H64M72E-400SBIF
W3H64M64E-400SBM	W3H64M72E-400SBM	W3H64M72E-400SBMF
W3H64M64E-533SBC	W3H64M72E-533SBC	W3H64M72E-533SBCF
W3H64M64E-533SBI	W3H64M72E-533SBI	W3H64M72E-533SBIF
W3H64M64E-533SBM	W3H64M72E-533SBM	W3H64M72E-533SBMF
3H64M64E-667SBC	W3H64M72E-667SBC	W3H64M72E-667SBCF
W3H64M64E-667SBI	W3H64M72E-667SBI	W3H64M72E-667SBIF
W3H64M64E-667SBM	W3H64M72E-667SBM	W3H64M72E-667SBMF

Microsemi Power and Microelectronics Group wishes to inform you of the following datasheet changes:

These changes apply to all products shipped from Microsemi Power and Microelectronics Group on or after November 9, 2011. Please contact your Sales representative for a revised datasheet or any questions related to this change.

Parameter	Unit	Original Spec	New Spec
tac_cl6_667mbs (max)	ps	450	650
tac_cl6_667mbx (min)	ps	-450	-300
tdqsck_cl6_667mbs (max)	ps	400	600
tdqsck_cl6_667mbs (min)	ps	-400	-300
tac_cl5_533mbs (min)	ps	500	650
tac_cl5_533mbs (max)	ps	-500	-400
tdqsck_cl5_533mbs (max)	ps	450	650
tdqsck_cl5_533mbs (min)	ps	-450	-350
tac_cl4_400mbs (max)	ps	600	800
tac_cl4_400mbs (min)	ps	-600	-500
tdqsck_cl4_400mbs (max)	ps	500	700
tdqsck_cl4_400mbs (min)	ps	-500	-400

As technology moves at a much faster pace, advanced embedded electronic components play a more strategic role. Constant changes and advancements in technology mandate that we anticipate changes and directions in technology for the benefit of our customers. As one of the pioneers in advanced semiconductor packaging and high-density memory solutions, we stand ready to assist you in managing this evolution of technology. If we can provide any additional assistance, please contact us at 602.437.1520 or complete a contact form at www.whiteedc.com/contact_us.html.

Best regards,
Microsemi Power and Microelectronics Group Engineering